

RoHS COMPLIANT HALOGEN

FREE

### SI1031R-T1-GE3-VB Datasheet

## P-Channel 20 V (D-S) MOSFET

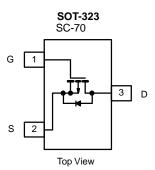
PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>c</sup>	Q <sub>g</sub> (Typ.)			
- 20	0.080 at V <sub>GS</sub> = - 4.5 V	- 3.1	4.3 nC			
- 20	0.100 at V <sub>GS</sub> = - 2.5 V	- 2.3	4.5110			

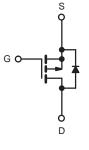
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

#### APPLICATIONS

- Load Switch
- DC/DC Converters





P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS (T</b>	A = 25 °C, unless oth	erwise noted)		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 20	V
Gate-Source Voltage		V <sub>GS</sub>	± 12	V
	T <sub>C</sub> = 25 °C		- 3.1	
Continuous Drain Current ( $T_J = 150 \text{ °C}$ )	T <sub>C</sub> = 70 °C		- 2.1	
Continuous Drain Current $(1) = 150^{\circ}$ C)	T <sub>A</sub> = 25 °C		- 1.4 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		- 1.1 <sup>a, b</sup>	A
Pulsed Drain Current	I <sub>DM</sub>	- 6		
Outline Outline Deale Dia la Outline I	T <sub>C</sub> = 25 °C	1-	- 0.4	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 0.3	
	T <sub>C</sub> = 25 °C		0.5	
	T <sub>C</sub> = 70 °C	P <sub>D</sub>	0.3	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	'D	0.4 <sup>a, b</sup>	vv
	T <sub>A</sub> = 70 °C		0.3 <sup>a, b</sup>	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 50 to 150	<u></u>
Soldering Recommendations (Peak Temperature)			260	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Based on T<sub>C</sub> = 25 °C.



THERMAL RESISTANCE RATINGS		
Baramotor	Symbol	

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a, b</sup>	t ≤ 10 s	R <sub>thJA</sub>	250	300	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	225	270	0/10

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. Maximum under steady state conditions is 360 °C/W.

<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		I	I			<b></b>	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA	- 20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μA		- 14		mV/°0	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	5,		2.4			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 0.45		- 1.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V$ , $V_{GS} = \pm 8 V$			± 100	nA	
Zero Gate Voltage Drain Current	lana	$V_{DS} = -20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	μA	
Zelo Gale voltage Drain Gurrent	IDSS	$V_{DS}$ = - 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 55 °C			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le$ - 5 V, $V_{GS}$ = - 4.5 V	- 2			Α	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1.4 A		0.080		Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 1.2 A		0.100			
		V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 0.3 A		0.140			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 1.4 A		5		S	
Dynamic <sup>b</sup>		-					
Input Capacitance	C <sub>iss</sub>			272			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		55		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			44			
·		V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1.4 A		4.3	6.5		
Total Gate Charge	Qg			2.7	4.1	nC	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 1.4 A		0.7			
Gate-Drain Charge	Q <sub>ad</sub>			1.0			
Gate Resistance	R <sub>a</sub>	f = 1 MHz	1.4	7	14	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			12	20		
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, \text{ R}_{\text{I}} = 9.1 \Omega$		20	30	- ns	
Turn-Off DelayTime		$I_D \cong -1.1 \text{ A}, \text{ V}_{\text{GEN}} = -4.5 \text{ V}, \text{ R}_g = 1 \Omega$		23	35		
Fall Time	t <sub>d(off)</sub> t <sub>f</sub>			9	18		
Turn-On Delay Time	-			5	10		
Rise Time	t <sub>d(on)</sub> t <sub>r</sub>			10	20		
Turn-Off DelayTime	-	$V_{DD}$ = - 10 V, R <sub>L</sub> = 9.1 Ω I <sub>D</sub> ≅ - 1.1 A, V <sub>GEN</sub> = - 8 V, R <sub>g</sub> = 1 Ω		10	20		
Fall Time	t <sub>d(off)</sub>	10 = 1.17, $0$ $GEN = 0.0, 10 = 1.22$		7	14		
	t <sub>f</sub>				14	L	
Drain-Source Body Diode Characterist Continuous Source-Drain Diode Current		T _ 25 %C	r		- 2.4	<u> </u>	
	I <sub>S</sub>	T <sub>C</sub> = 25 °C				A	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			0.0	- 6	\ <u>\</u>	
Body Diode Voltage	V <sub>SD</sub>	I <sub>F</sub> = - 0.7 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	4		18	27	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>E</sub> = - 0.7 A, dl/dt = 100 A/μs, T <sub>1</sub> = 25 °C		7	14	nC	
Reverse Recovery Fall Time	t <sub>a</sub>			7		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			11			

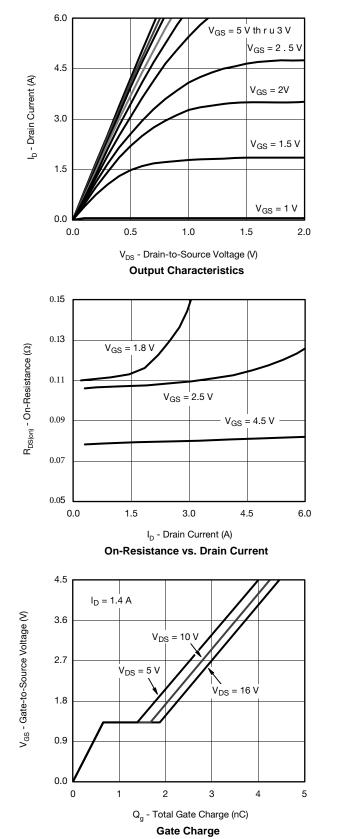
Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

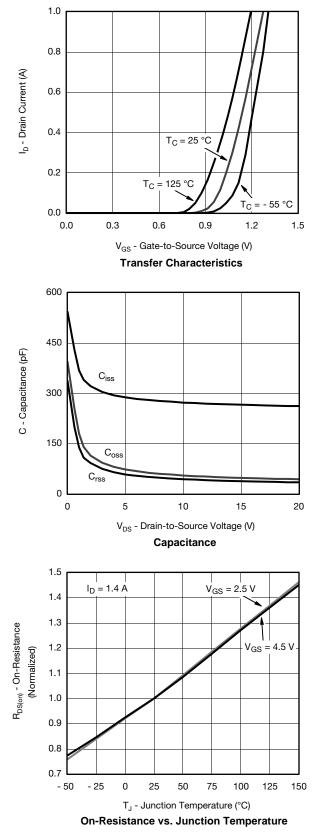
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





I<sub>D</sub> = 1.4 A

T<sub>J</sub> = 125 °C

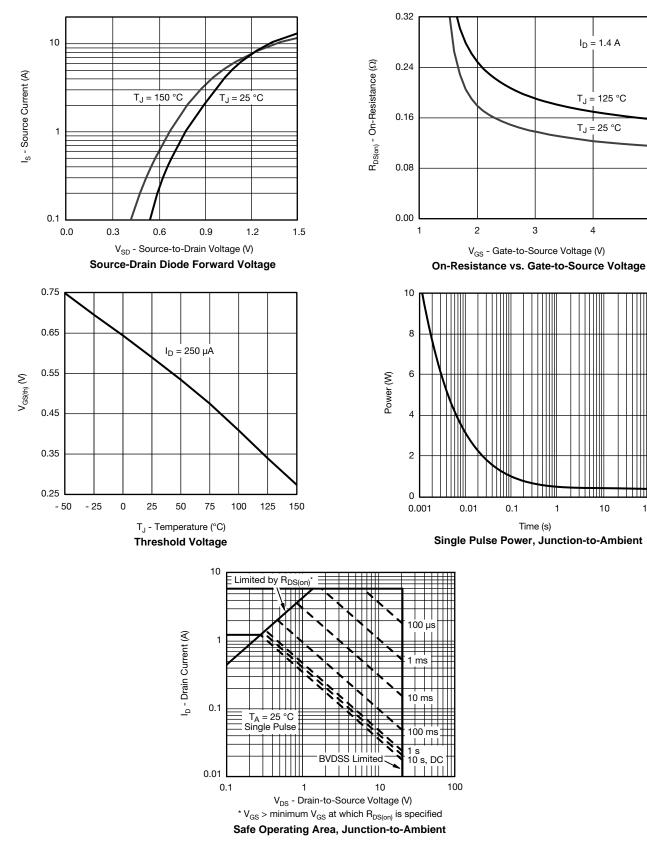
 $T_J = 25 \ ^\circ C$ 

4

10

100

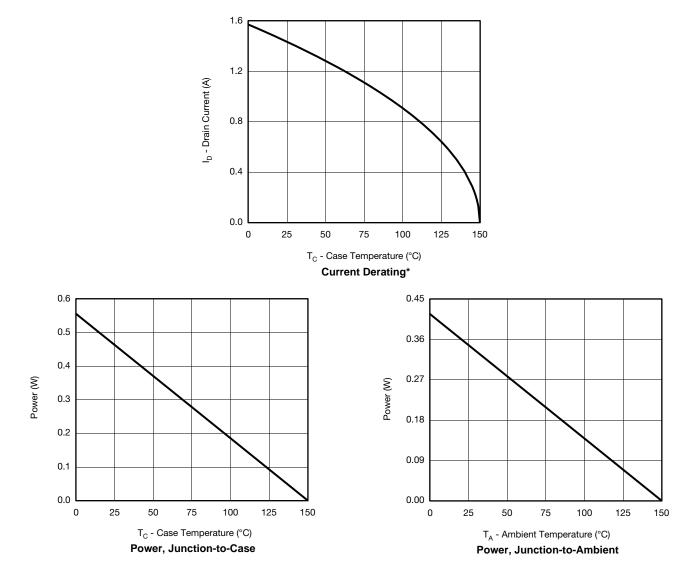
5



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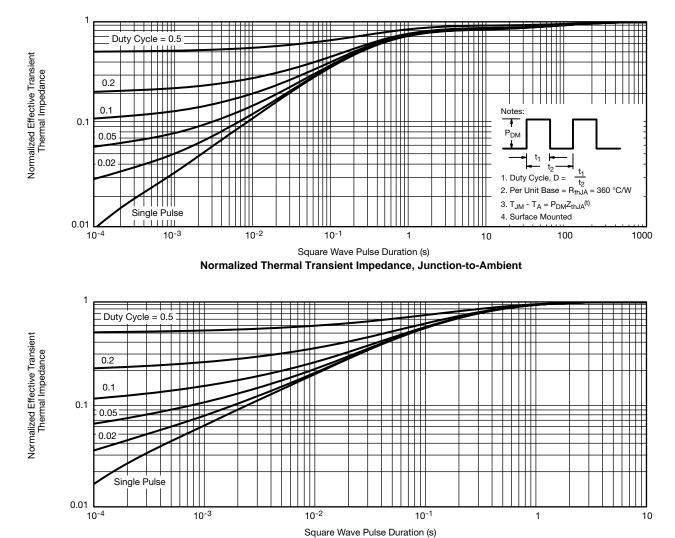


#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





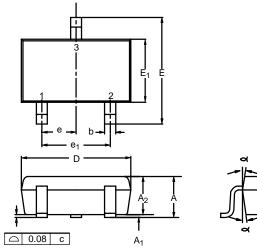
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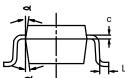
Normalized Thermal Transient Impedance, Junction-to-Foot

## SI1031R-T1-GE3-VB



#### SC-70: 3-LEADS



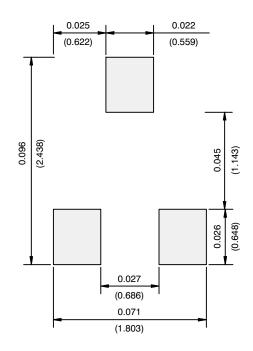


	MILLIMETERS			INCHES				
Dim	Min	Nom	Max	Min	Min Nom			
Α	0.90	-	1.10	0.035	-	0.043		
<b>A</b> <sub>1</sub>	-	-	0.10	-	-	0.004		
A <sub>2</sub>	0.80	-	1.00	0.031	-	0.039		
b	0.25	-	0.40	0.010	-	0.016		
С	0.10	-	0.25	0.004 –		0.010		
D	1.80	2.00	2.20	0.071 0.079		0.087		
E	1.80	2.10	2.40	0.071 0.083 0.0		0.094		
E <sub>1</sub>	1.15	1.25	1.35	0.045 0.049 0.05				
е	0.65BSC			0.026BSC				
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055		
L	0.10	0.20	0.30	0.004 0.008		0.012		
٩	7°Nom			7°Nom				
ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549								

## SI1031R-T1-GE3-VB



#### **RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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